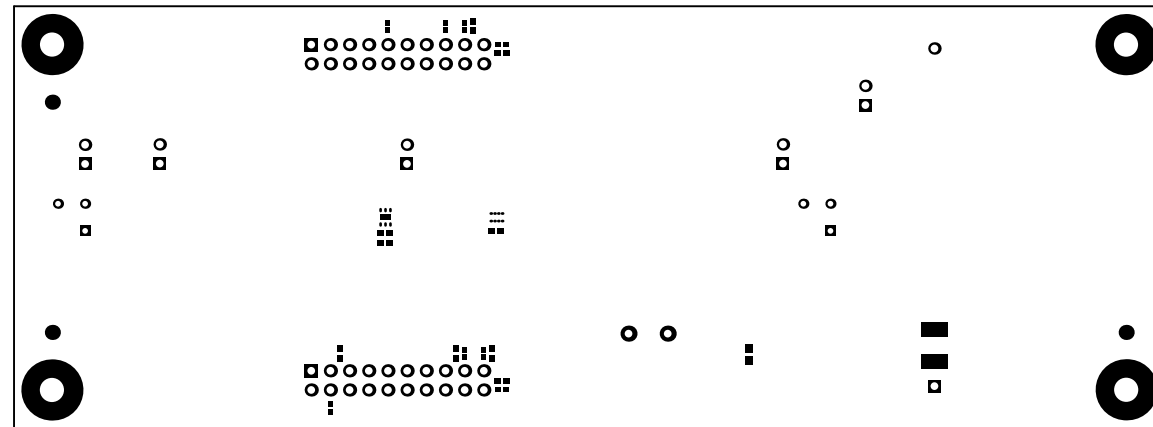
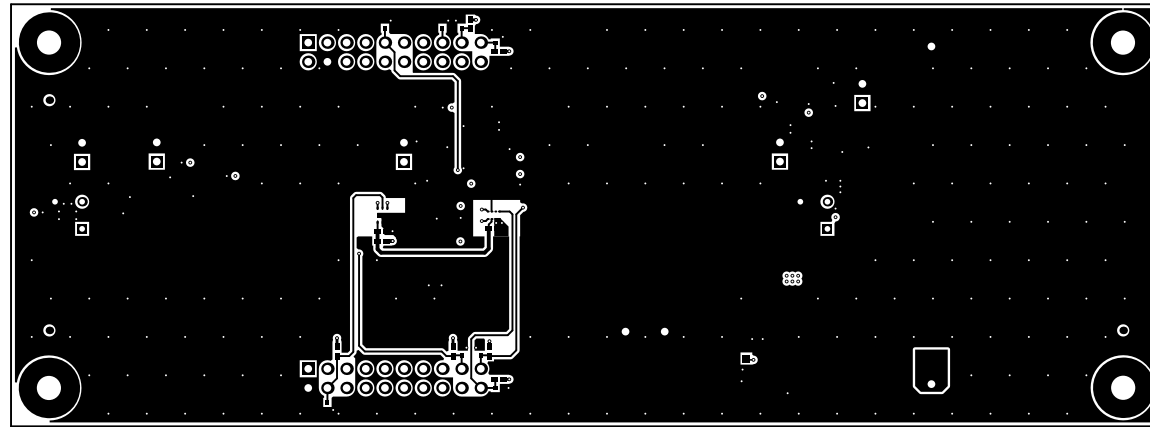


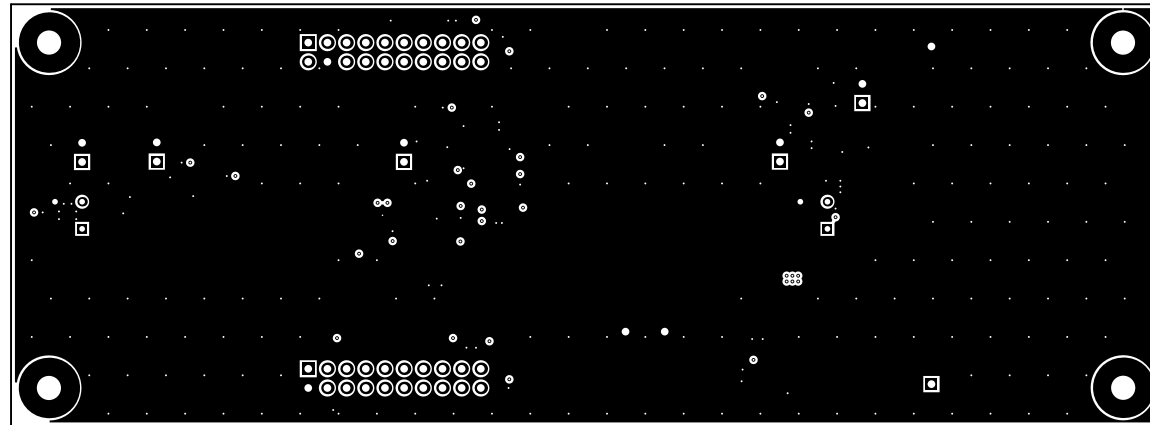
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01069	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: 01069		
PLOT NAME = Top Overlay	GENERATED : 28/02/2017 15:19:36		TEXAS INSTRUMENTS



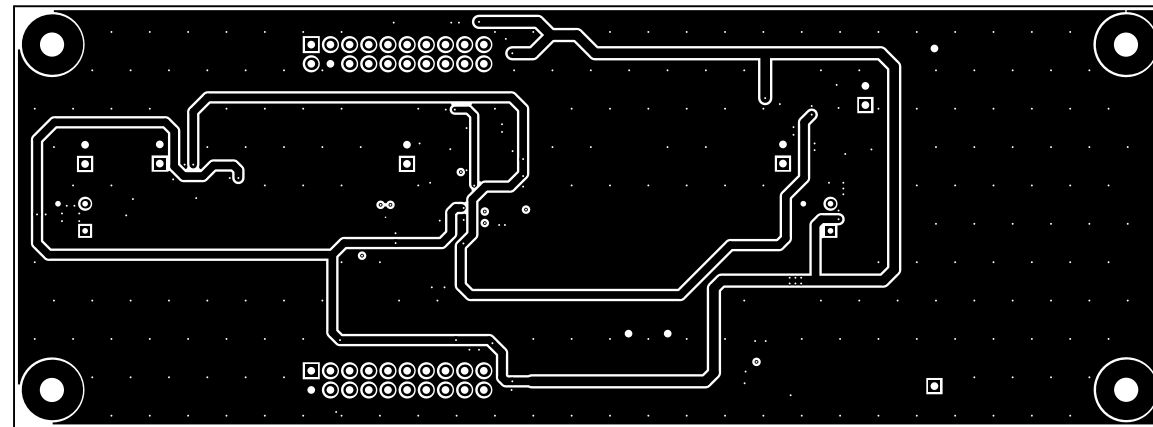
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01069	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: 01069		
PLOT NAME = Top Solder Mask	GENERATED : 28/02/2017 15:19:36	TEXAS INSTRUMENTS	



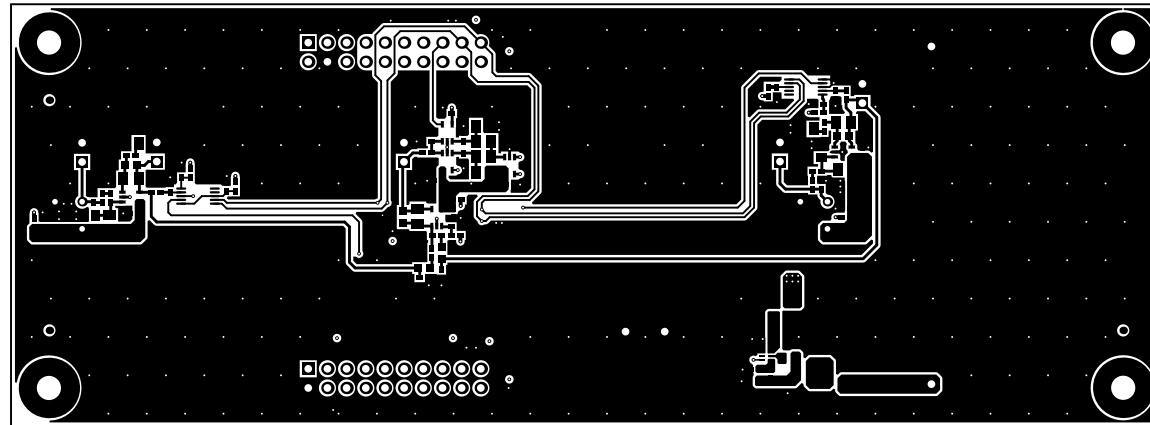
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01069	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer	TID #: 01069		
PLOT NAME = Top Layer	GENERATED : 28/02/2017 15:19:37	TEXAS INSTRUMENTS	



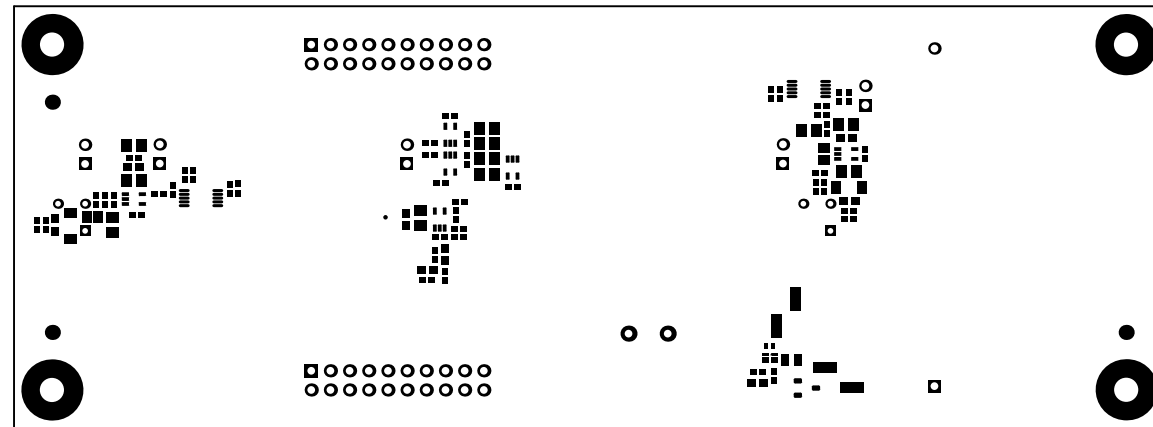
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01069	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 2 - GND	TID #: 01069		
PLOT NAME = Signal Layer 1	GENERATED : 28/02/2017 15:19:38	TEXAS INSTRUMENTS	



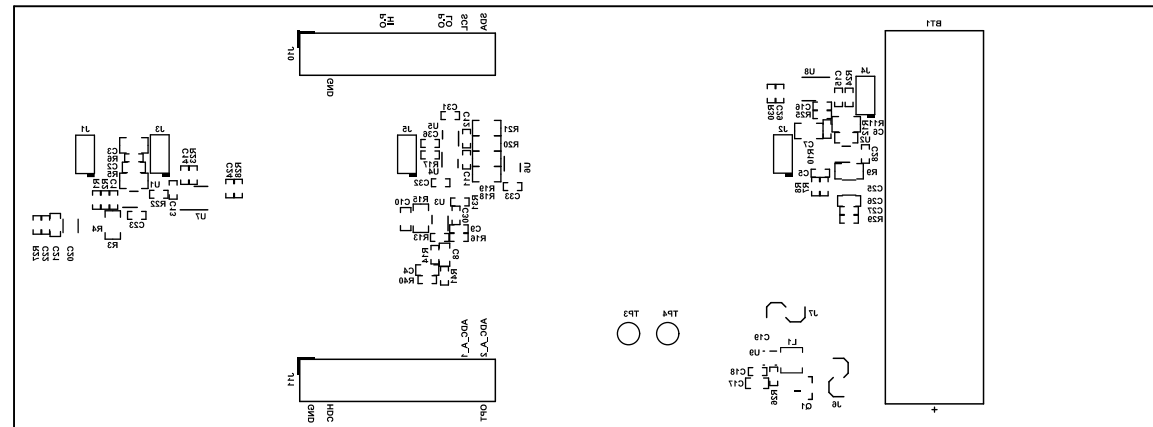
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01069	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 3 - PWR	TID #: 01069		
PLOT NAME = Signal Layer 2	GENERATED : 28/02/2017 15:19:39	TEXAS INSTRUMENTS	



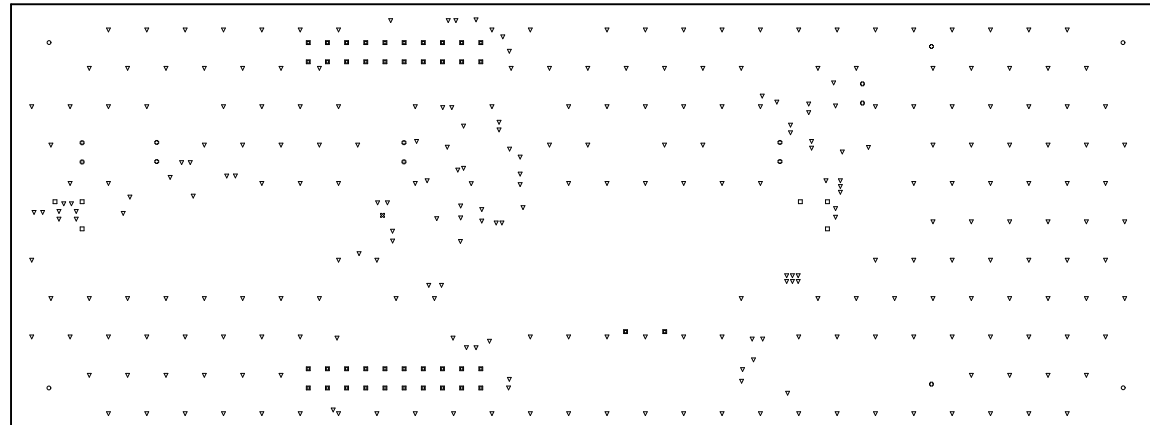
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01069	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - Bottom Layer	TID #: 01069		
PLOT NAME = Bottom Layer	GENERATED : 28/02/2017 15:19:40	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01069	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: 01069		
PLOT NAME = Bottom Solder Mask	GENERATED : 28/02/2017 15:19:41	TEXAS INSTRUMENTS	

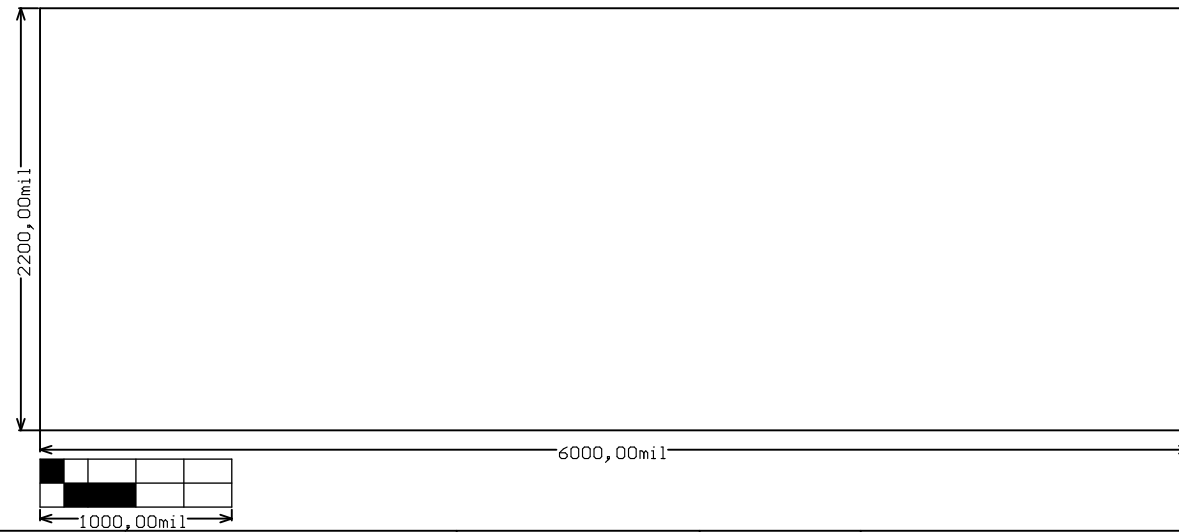


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01069	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: 01069		
PLOT NAME = Bottom Overlay	GENERATED : 28/02/2017 15:19:42		TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊠	1	7.87mil (0.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
▽	286	10.00mil (0.254mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
□	6	29.53mil (0.750mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
⊞	42	40.00mil (1.016mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
⊕	12	40.16mil (1.020mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
○	4	125.98mil (3.200mm)	PTH	Round	Layer 1 - Top Layer - Layer 4 - Bottom Layer	
	351 Total					

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01069	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: 01069		
PLOT NAME = Drill Drawing	GENERATED : 28/02/2017 15:19:43	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01069	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: 01069		
PLOT NAME = Board Dimensions	GENERATED : 28/02/2017 15:19:44	TEXAS INSTRUMENTS	

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